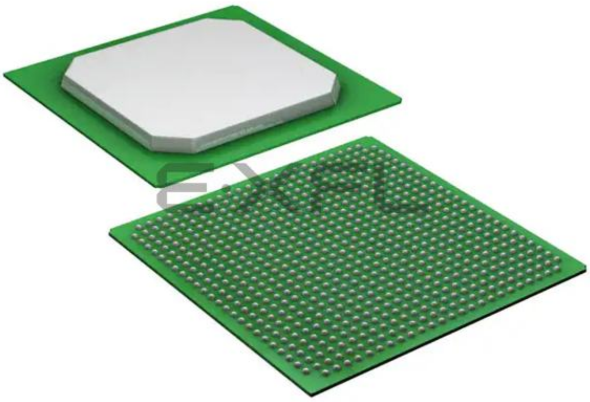
Intel - EP2C50F672I8 Datasheet



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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

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The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	3158
Number of Logic Elements/Cells	50528
Total RAM Bits	594432
Number of I/O	450
Number of Gates	-
Voltage - Supply	1.15V ~ 1.25V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	672-BGA
Supplier Device Package	672-FBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep2c50f672i8

About This Handbook

This handbook provides comprehensive information about the Altera® Cyclone® II family of devices.

How to Contact Altera

For the most up-to-date information about Altera products, refer to the following table.

Contact (1)	Contact Method	Address
Technical support	Website	www.altera.com/support
Technical training	Website	www.altera.com/training
	Email	custrain@altera.com
Product literature	Website	www.altera.com/literature
Altera literature services	Email	literature@altera.com
Non-technical support (General)	Email	nacomp@altera.com
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Note to table:

(1) You can also contact your local Altera sales office or sales representative.

Typographic Conventions

This document uses the typographic conventions shown below.

Visual Cue	Meaning
Bold Type with Initial Capital Letters	Command names, dialog box titles, checkbox options, and dialog box options are shown in bold, initial capital letters. Example: **Save As** dialog box.
bold type	External timing parameters, directory names, project names, disk drive names, filenames, filename extensions, and software utility names are shown in bold type. Examples: $\mathbf{f_{MAX}}$, **\qdesigns** directory, **d:** drive, **chiptrip.gdf** file.
Italic Type with Initial Capital Letters	Document titles are shown in italic type with initial capital letters. Example: *AN 75: High-Speed Board Design.*

Another special packing mode allows the register output to feed back into the LUT of the same LE so that the register is packed with its own fan-out LUT, providing another mechanism for improved fitting. The LE can also drive out registered and unregistered versions of the LUT output.

In addition to the three general routing outputs, the LEs within an LAB have register chain outputs. Register chain outputs allow registers within the same LAB to cascade together. The register chain output allows an LAB to use LUTs for a single combinational function and the registers to be used for an unrelated shift register implementation. These resources speed up connections between LABs while saving local interconnect resources. See "MultiTrack Interconnect" on page 2–10 for more information on register chain connections.

LE Operating Modes

The Cyclone II LE operates in one of the following modes:

- Normal mode
- Arithmetic mode

Each mode uses LE resources differently. In each mode, six available inputs to the LE—the four data inputs from the LAB local interconnect, the LAB carry-in from the previous carry-chain LAB, and the register chain connection—are directed to different destinations to implement the desired logic function. LAB-wide signals provide clock, asynchronous clear, synchronous clear, synchronous load, and clock enable control for the register. These LAB-wide signals are available in all LE modes.

The Quartus® II software, in conjunction with parameterized functions such as library of parameterized modules (LPM) functions, automatically chooses the appropriate mode for common functions such as counters, adders, subtractors, and arithmetic functions. If required, you can also create special-purpose functions that specify which LE operating mode to use for optimal performance.

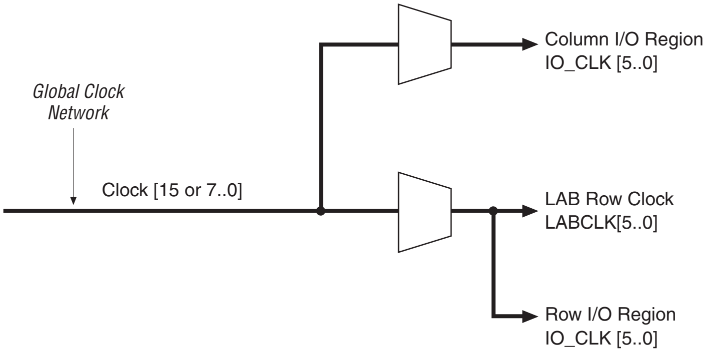
Normal Mode

The normal mode is suitable for general logic applications and combinational functions. In normal mode, four data inputs from the LAB local interconnect are inputs to a four-input LUT (see Figure 2–3). The Quartus II Compiler automatically selects the carry-in or the `data3` signal as one of the inputs to the LUT. LEs in normal mode support packed registers and register feedback.

Global Clock Network Distribution

Cyclone II devices contains 16 global clock networks. The device uses multiplexers with these clocks to form six-bit buses to drive column IOE clocks, LAB row clocks, or row IOE clocks (see Figure 2–14). Another multiplexer at the LAB level selects two of the six LAB row clocks to feed the LE registers within the LAB.

Figure 2–14. Global Clock Network Multiplexers



LAB row clocks can feed LEs, M4K memory blocks, and embedded multipliers. The LAB row clocks also extend to the row I/O clock regions.

IOE clocks are associated with row or column block regions. Only six global clock resources feed to these row and column regions. Figure 2–15 shows the I/O clock regions.

Table 5–16. LE_FF Internal Timing Microparameters (Part 2 of 2)							
Parameter	–6 Speed Grade *(1)*		–7 Speed Grade *(2)*		–8 Speed Grade *(3)*		Unit
	Min	Max	Min	Max	Min	Max	
TPRE	191	—	244	—	244	—	ps
	—	—	217	—	244	—	ps
TCLKL	1000	—	1242	—	1242	—	ps
	—	—	1111	—	1242	—	ps
TCLKH	1000	—	1242	—	1242	—	ps
	—	—	1111	—	1242	—	ps
tLUT	180	438	172	545	172	651	ps
	—	—	180	—	180	—	ps

Notes to Table 5–16:

(1) For the –6 speed grades, the minimum timing is for the commercial temperature grade. The –7 speed grade devices offer the automotive temperature grade. The –8 speed grade devices offer the industrial temperature grade.

(2) For each parameter of the –7 speed grade columns, the value in the first row represents the minimum timing parameter for automotive devices. The second row represents the minimum timing parameter for commercial devices.

(3) For each parameter of the –8 speed grade columns, the value in the first row represents the minimum timing parameter for industrial devices. The second row represents the minimum timing parameter for commercial devices.

Table 5–17. IOE Internal Timing Microparameters (Part 1 of 2)							
Parameter	–6 Speed Grade *(1)*		–7 Speed Grade *(2)*		–8 Speed Grade *(3)*		Unit
	Min	Max	Min	Max	Min	Max	
TSU	76	—	101	—	101	—	ps
	—	—	89	—	101	—	ps
TH	88	—	106	—	106	—	ps
	—	—	97	—	106	—	ps
TCO	99	155	95	171	95	187	ps
	—	—	99	—	99	—	ps
TPIN2COMBOUT_R	384	762	366	784	366	855	ps
	—	—	384	—	384	—	ps
TPIN2COMBOUT_C	385	760	367	783	367	854	ps
	—	—	385	—	385	—	ps
TCOMBIN2PIN_R	1344	2490	1280	2689	1280	2887	ps
	—	—	1344	—	1344	—	ps

Table 5–17. IOE Internal Timing Microparameters (Part 2 of 2)							
Parameter	**–6 Speed Grade** *(1)*		**–7 Speed Grade** *(2)*		**–8 Speed Grade** *(3)*		**Unit**
	Min	**Max**	**Min**	**Max**	**Min**	**Max**	
TCOMBIN2PIN_C	1418	2622	1352	2831	1352	3041	ps
	—	—	1418	—	1418	—	ps
TCLR	137	—	165	—	165	—	ps
	—	—	151	—	165	—	ps
TPRE	192	—	233	—	233	—	ps
	—	—	212	—	233	—	ps
TCLKL	1000	—	1242	—	1242	—	ps
	—	—	1111	—	1242	—	ps
TCLKH	1000	—	1242	—	1242	—	ps
	—	—	1111	—	1242	—	ps

Notes to Table 5–17:

(1) For the –6 speed grades, the minimum timing is for the commercial temperature grade. The –7 speed grade devices offer the automotive temperature grade. The –8 speed grade devices offer the industrial temperature grade.

(2) For each parameter of the –7 speed grade columns, the value in the first row represents the minimum timing parameter for automotive devices. The second row represents the minimum timing parameter for commercial devices.

(3) For each parameter of the –8 speed grade columns, the value in the first row represents the minimum timing parameter for industrial devices. The second row represents the minimum timing parameter for commercial devices.

Table 5–18. DSP Block Internal Timing Microparameters (Part 1 of 2)							
Parameter	**–6 Speed Grade** *(1)*		**–7 Speed Grade** *(2)*		**–8 Speed Grade** *(3)*		**Unit**
	Min	**Max**	**Min**	**Max**	**Min**	**Max**	
TSU	47	—	62	—	62	—	ps
	—	—	54	—	62	—	ps
TH	110	—	113	—	113	—	ps
	—	—	111	—	113	—	ps
TCO	0	0	0	0	0	0	ps
	—	—	0	—	0	—	ps
TINREG2PIPE9	652	1379	621	1872	621	2441	ps
	—	—	652	—	652	—	ps
TINREG2PIPE18	652	1379	621	1872	621	2441	ps
	—	—	652	—	652	—	ps

Table 5–37. Cyclone II IOE Programmable Delay on Row Pins Notes (1), (2) (Part 2 of 2)											
Parameter	**Paths Affected**	**Number of Settings**	**Fast Corner (3)**		**–6 Speed Grade**		**–7 Speed Grade (4)**		**–8 Speed Grade**		**Unit**
			Min Offset	**Max Offset**	**Min Offset**	**Max Offset**	**Min Offset**	**Max Offset**	**Min Offset**	**Max Offset**	
Input Delay from Pin to Input Register	Pad -> I/O input register	8	0	2669	0	4482	0	4834	0	4859	ps
			0	2802	—	—	0	4671	—	—	ps
Delay from Output Register to Output Pin	I/O output register -> Pad	2	0	308	0	572	0	648	0	682	ps
			0	324	—	—	0	626	—	—	ps

Notes to Table 5–37 :

(1) The incremental values for the settings are generally linear. For exact values of each setting, use the latest version of the Quartus II software.

(2) The minimum and maximum offset timing numbers are in reference to setting "0" as available in the Quartus II software.

(3) The value in the first row represents the fast corner timing parameter for industrial and automotive devices. The second row represents the fast corner timing parameter for commercial devices.

(4) The value in the first row is for automotive devices. The second row is for commercial devices.

Default Capacitive Loading of Different I/O Standards

Refer to Table 5–38 for default capacitive loading of different I/O standards.

Table 5–38. Default Loading of Different I/O Standards for Cyclone II Device (Part 1 of 2)		
I/O Standard	**Capacitive Load**	**Unit**
LVTTL	0	pF
LVCMOS	0	pF
2.5V	0	pF
1.8V	0	pF
1.5V	0	pF
PCI	10	pF
PCI-X	10	pF
SSTL_2_CLASS_I	0	pF
SSTL_2_CLASS_II	0	pF
SSTL_18_CLASS_I	0	pF

Table 5–44. Maximum Input Clock Toggle Rate on Cyclone II Devices (Part 2 of 2)									
I/O Standard	**Maximum Input Clock Toggle Rate on Cyclone II Devices (MHz)**								
	Column I/O Pins			**Row I/O Pins**			**Dedicated Clock Inputs**		
	–6 Speed Grade	**–7 Speed Grade**	**–8 Speed Grade**	**–6 Speed Grade**	**–7 Speed Grade**	**–8 Speed Grade**	**–6 Speed Grade**	**–7 Speed Grade**	**–8 Speed Grade**
DIFFERENTIAL_SSTL_18_ CLASS_I	500	500	500	500	500	500	500	500	500
DIFFERENTIAL_SSTL_18_ CLASS_II	500	500	500	500	500	500	500	500	500
1.8V_DIFFERENTIAL_HSTL_ CLASS_I	500	500	500	500	500	500	500	500	500
1.8V_DIFFERENTIAL_HSTL_ CLASS_II	500	500	500	500	500	500	500	500	500
1.5V_DIFFERENTIAL_HSTL_ CLASS_I	500	500	500	500	500	500	500	500	500
1.5V_DIFFERENTIAL_HSTL_ CLASS_II	500	500	500	500	500	500	500	500	500
LVPECL	—	—	—	—	—	—	402	402	402
LVDS	402	402	402	402	402	402	402	402	402
1.2V_HSTL	110	90	80	—	—	—	110	90	80
1.2V_DIFFERENTIAL_HSTL	110	90	80	—	—	—	110	90	80

Table 5–45. Maximum Output Clock Toggle Rate on Cyclone II Devices (Part 1 of 4)										
I/O Standard	**Drive Strength**	**Maximum Output Clock Toggle Rate on Cyclone II Devices (MHz)**								
		Column I/O Pins *(1)*			**Row I/O Pins** *(1)*			**Dedicated Clock Outputs**		
		–6 Speed Grade	**–7 Speed Grade**	**–8 Speed Grade**	**–6 Speed Grade**	**–7 Speed Grade**	**–8 Speed Grade**	**–6 Speed Grade**	**–7 Speed Grade**	**–8 Speed Grade**
LVTTL	4 mA	120	100	80	120	100	80	120	100	80
	8 mA	200	170	140	200	170	140	200	170	140
	12 mA	280	230	190	280	230	190	280	230	190
	16 mA	290	240	200	290	240	200	290	240	200
	20 mA	330	280	230	330	280	230	330	280	230
	24 mA	360	300	250	360	300	250	360	300	250

Table 7–6. I/O Standards Supported for Cyclone II PLLs (Part 2 of 2)

I/O Standard	Input	Output	
	inclk	lock	pll_out
SSTL-25 class II	✓	✓	✓
RSDS/mini-LVDS *(4)*		✓	✓

Notes to Table 7–6:
(1) The PCI-X I/O standard is supported only on side I/O pins.
(2) Differential SSTL and HSTL outputs are only supported on the `PLL<#>_OUT` pins.
(3) These I/O standards are only supported on top and bottom I/O pins.
(4) The RSDS and mini-LVDS pins are only supported on output pins.

Clock Feedback Modes

Cyclone II PLLs support four clock feedback modes: normal mode, zero delay buffer mode, no compensation mode, and source synchronous mode. Cyclone II PLLs do not have support for external feedback mode. All the supported clock feedback modes allow for multiplication and division, phase shifting, and programmable duty cycle. The phase relationships shown in the waveforms in Figures 7–4 through 7–6 are for the default (zero degree) phase shift setting. Changing the phase-shift setting changes the relationships between the output clocks from the PLL.

Normal Mode

In normal mode, the PLL phase-aligns the input reference clock with the clock signal at the ports of the registers in the logic array I/O registers to compensate for the internal global clock network delay. Use the `altpll` megafunction in the Quartus II software to define which internal clock output from the PLL (c0, c1, or c2) to compensate for.

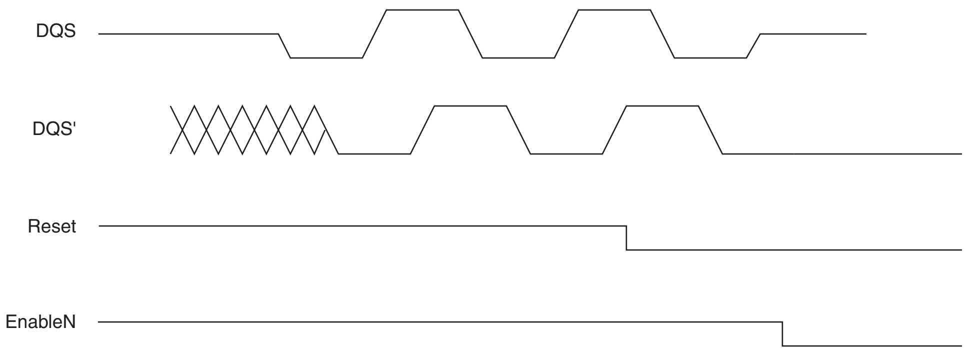
If an external clock output pin (`PLL<#>_OUT`) is used in this mode, there is a phase shift with respect to the clock input pin. Similarly, if the internal PLL clock outputs are used to drive general-purpose I/O pins, there is be phase shift with respect to the clock input pin.

Figure 7–4 shows an example waveform of the PLL clocks' phase relationship in this mode.

Table 7–8. Global Clock Network Connections (Part 2 of 3)

Global Clock Network Clock Sources	Global Clock Networks															
	All Cyclone II Devices								EP2C15 through EP2C70 Devices Only							
	0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15
PLL4_c0													✓	✓		✓
PLL4_c1													✓		✓	✓
PLL4_c2														✓	✓	
DPCLK0 *(1)*	✓															
DPCLK1 *(1)*		✓														
DPCLK10 *(1)*, *(2)* CDPCLK0 or CDPCLK7 *(3)*			✓													
DPCLK2 *(1)*, *(2)* CDPCLK1 or CDPCLK2 *(3)*				✓												
DPCLK7 *(1)*					✓											
DPCLK6 *(1)*						✓										
DPCLK8 *(1)*, *(2)* CDPCLK5 or CDPCLK6 *(3)*							✓									
DPCLK4 *(1)*, *(2)* CDPCLK4 or CDPCLK3 *(3)*								✓								
DPCLK8 *(1)*									✓							
DPCLK11 *(1)*										✓						
DPCLK9 *(1)*											✓					
DPCLK10 *(1)*												✓				
DPCLK5 *(1)*													✓			
DPCLK2 *(1)*														✓		
DPCLK4 *(1)*															✓	

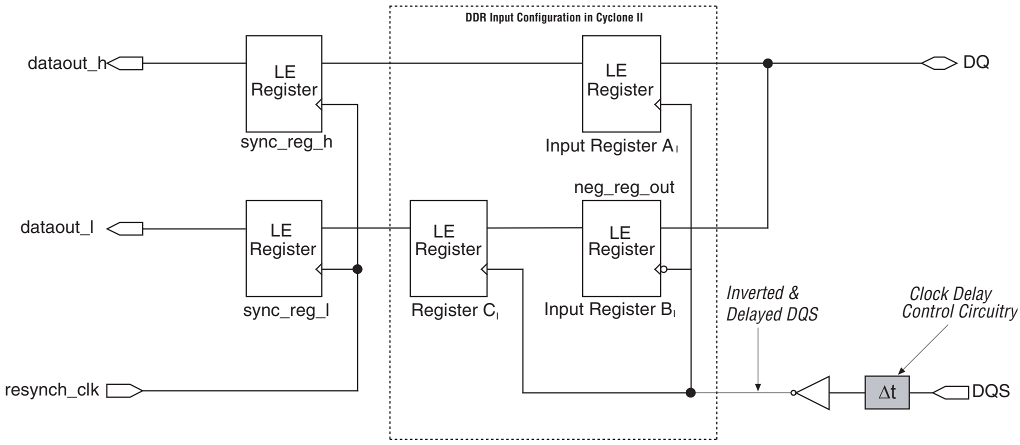
Figure 9–10. Cyclone II DQS Postamble Circuitry Control Timing Waveform



DDR Input Registers

In Cyclone II devices, the DDR input registers are implemented with five internal LE registers located in the logic array block (LAB) adjacent to the DDR input pin (see Figure 9–11). The DDR data is fed to the first two registers, input register A_I and input register B_I. Input register B_I captures the DDR data present during the rising edge of the clock. Input register A_I captures the DDR data present during the falling edge of the clock. Register C_I aligns the data before it is transferred to the resynchronization registers.

Figure 9–11. DDR Input Implementation



I/O Termination

The majority of the Cyclone II I/O standards are single-ended, non-voltage-referenced I/O standards and, as such, the following I/O standards do not specify a recommended termination scheme:

- 3.3-V LVTTL and LVCMOS
- 2.5-V LVTTL and LVCMOS
- 1.8-V LVTTL and LVCMOS
- 1.5-V LVCMOS
- 3.3-V PCI and PCI-X

Voltage-Referenced I/O Standard Termination

Voltage-referenced I/O standards require both an input reference voltage, V_{REF}, and a termination voltage, V_{TT}. The reference voltage of the receiving device tracks the termination voltage of the transmitting device.

For more information on termination for voltage-referenced I/O standards, refer to "Supported I/O Standards" on page 10–1.

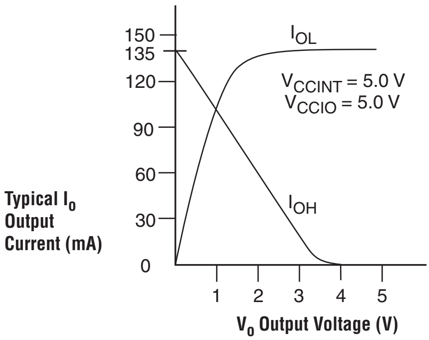
Differential I/O Standard Termination

Differential I/O standards typically require a termination resistor between the two signals at the receiver. The termination resistor must match the differential load impedance of the bus.

Cyclone II devices support differential I/O standards LVDS, RSDS, and mini-LVDS, and differential LVPECL.

For more information on termination for differential I/O standards, refer to "Supported I/O Standards" on page 10–1.

Figure 10–22. Output Drive Characteristics of a 5.0-V Device



As shown above, R_1 = 5.0-V/135 mA.

☞ The values shown in data sheets usually reflect typical operating conditions. Subtract 20% from the data sheet value for guard band. This subtraction when applied in the example in Figure 10–22 gives R_1 a value of 30 Ω

R_2 should be selected so that it does not violate the driving device's I_{OH} specification. For example, if the device has a maximum I_{OH} of 8 mA, given that the PCI clamping diode, $V_{IN} = V_{CCIO}$ + 0.7-V = 3.7-V, and the maximum supply load of a 5.0-V device (V_{CC}) is 5.25-V, the value of R_2 can be calculated as follows:

$$R_2 = \frac{(5.25\text{ V} - 3.7\text{ V}) - (8\text{ mA} \times 30\ \Omega)}{8\text{ mA}} = 164\ \Omega$$

This analysis assumes worst case conditions. If your system does not have a wide variation in voltage-supply levels, you can adjust these calculations accordingly.

☞ Because 5.0-V device tolerance in Cyclone II devices requires use of the PCI clamp, and this clamp is activated during configuration, 5.0-V signals may not be driven into the device until it is configured.

Conclusion

Cyclone II device I/O capabilities enable you to keep pace with increasing design complexity utilizing a low-cost FPGA device family. Support for I/O standards including SSTL and LVDS compatibility allow Cyclone II devices to fit into a wide variety of applications. The Quartus II software makes it easy to use these I/O standards in Cyclone II device designs. After design compilation, the software also provides clear, visual representations of pads and pins and the selected I/O standards. Taking advantage of the support of these I/O standards in Cyclone II devices allows you to lower your design costs without compromising design flexibility or complexity.

References

For more information on the I/O standards referred to in this document, refer to the following sources:

- Stub Series Terminated Logic for 2.5-V (SSTL-2), JESD8-9A, Electronic Industries Association, December 2000.
- 1.5-V +/- 0.1-V (Normal Range) and 0.9-V - 1.6-V (Wide Range) Power Supply Voltage and Interface Standard for Non-terminated Digital Integrated Circuits, JESD8-11, Electronic Industries Association, October 2000.
- 1.8-V +/- 0.15-V (Normal Range) and 1.2-V - 1.95-V (Wide Range) Power Supply Voltage and Interface Standard for Non-terminated Digital Integrated Circuits, JESD8-7, Electronic Industries Association, February 1997.
- 2.5-V +/- 0.2-V (Normal Range) and 1.8-V to 2.7-V (Wide Range) Power Supply Voltage and Interface Standard for Non-terminated Digital Integrated Circuits, JESD8-5, Electronic Industries Association, October 1995.
- Interface Standard for Nominal 3-V/ 3.3-V Supply Digital Integrated Circuits, JESD8-B, Electronic Industries Association, September 1999.
- PCI Local Bus Specification, Revision 2.2, PCI Special Interest Group, December 1998.
- Electrical Characteristics of Low Voltage Differential Signaling (LVDS) Interface Circuits, ANSI/TIA/EIA-644, American National Standards Institute/Telecommunications Industry/Electronic Industries Association, October 1995.

Figure 11–12. Differential SSTL Class I Interface

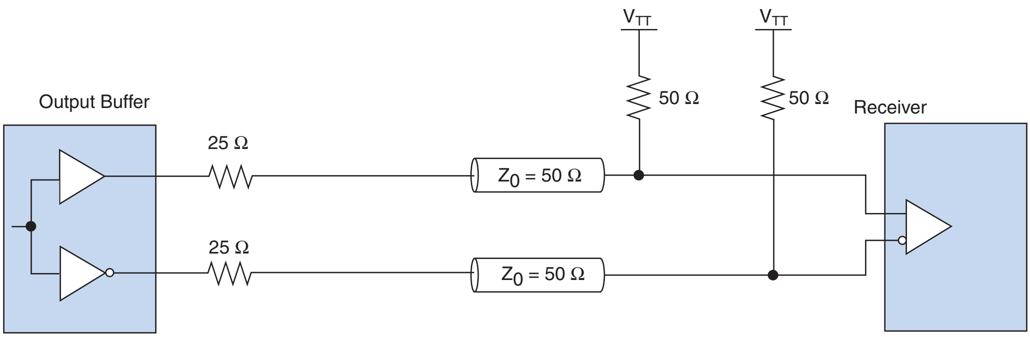
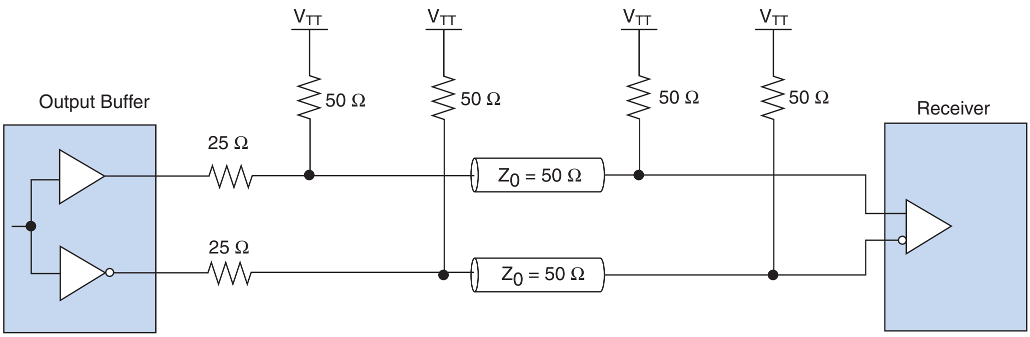


Figure 11–13. Differential SSTL Class II Interface



Differential HSTL Support in Cyclone II Devices

The differential HSTL AC and DC specifications are the same as the HSTL single-ended specifications. The differential HSTL I/O standard is available on the `GCLK` pins only, treating differential inputs as two single-ended HSTL, and only decoding one of them. The differential HSTL output I/O standard is only supported at the `PLLCLKOUT` pins using two single-ended HSTL output buffers with the second output programmed as inverted. The standard requires two differential inputs with an external termination voltage (V_{TT}) of $0.5 \times V_{CCIO}$ to which termination resistors are connected.

For the HSTL signaling characteristics, see the *DC Characteristics & Timing Specifications* chapter and the *Selectable I/O Standards in Cyclone II Devices* chapter in Volume 1 of the *Cyclone II Device Handbook.*

Table 11–5 defines the parameters of the timing diagram shown in Figure 11–16. Figure 11–17 shows the Cyclone II high-speed I/O timing budget.

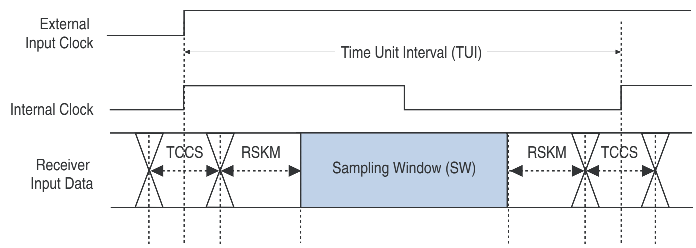
Table 11–5. High-Speed I/O Timing Definitions

Parameter	Symbol	Description
Transmitter channel-to-channel skew *(1)*	TCCS	The timing difference between the fastest and slowest output edges, including t_{CO} variation and clock skew. The clock is included in the TCCS measurement.
Sampling window	SW	The period of time during which the data must be valid in order for you to capture it correctly. The setup and hold times determine the ideal strobe position within the sampling window. $T_{SW} = T_{SU} + T_{hd}$ + PLL jitter.
Receiver input skew margin	RSKM	RSKM is defined by the total margin left after accounting for the sampling window and TCCS. The RSKM equation is: RSKM = (TUI – SW – TCCS) / 2.
Input jitter tolerance (peak-to-peak)		Allowed input jitter on the input clock to the PLL that is tolerable while maintaining PLL lock.
Output jitter (peak-to-peak)		Peak-to-peak output jitter from the PLL.

Note to Table 11–5:

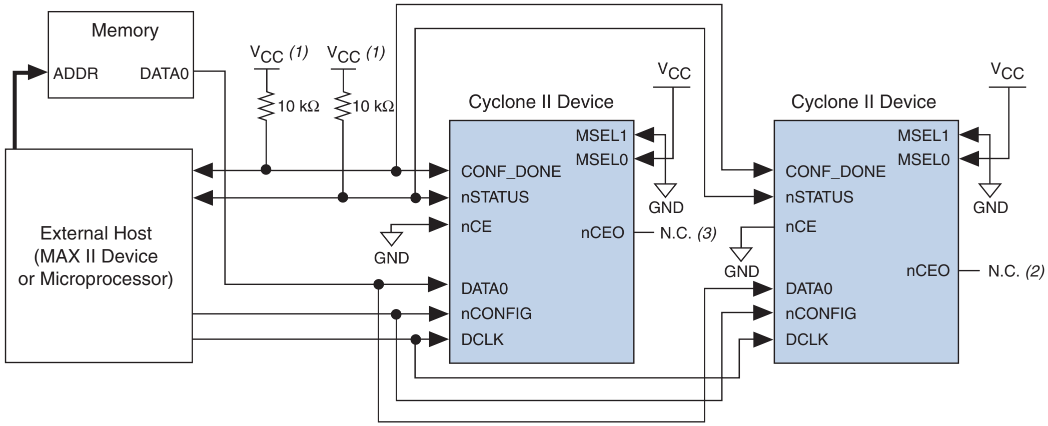
(1) The TCCS specification applies to the entire bank of LVDS as long as the SERDES logic are placed within the LAB adjacent to the output pins.

Figure 11–16. High-Speed I/O Timing Diagram



If your system has multiple Cyclone II devices (in the same density and package) with the same configuration data, you can configure them in one configuration cycle by connecting all device's nCE pins to ground and connecting all the Cyclone II device's configuration pins (nCONFIG, nSTATUS, DCLK, DATA0, and CONF_DONE) together. You can also use the nCEO pin as a user I/O pin after configuration. The configuration signals may require buffering to ensure signal integrity and prevent clock skew problems. Make sure the DCLK and DATA lines are buffered for every fourth device. All devices start and complete configuration at the same time. Figure 13–11 shows multiple device PS configuration when both Cyclone II devices are receiving the same configuration data.

Figure 13–11. Multiple Device PS Configuration When Both FPGAs Receive the Same Data



Notes to Figure 13–11:

(1) The pull-up resistor should be connected to a supply that provides an acceptable input signal for all devices in the chain. V_{CC} should be high enough to meet the V_{IH} specification of the I/O on the devices and the external host.

(2) The nCEO pins of both devices can be left unconnected or used as user I/O pins when configuring the same configuration data into multiple devices.

You can use a single configuration chain to configure Cyclone II devices with other Altera devices. Connect all the Cyclone II device's and all other Altera device's CONF_DONE and nSTATUS pins together so all devices in the chain complete configuration at the same time or that an error reported by one device initiates reconfiguration in all devices.

For more information on configuring multiple Altera devices in the same configuration chain, see *Configuring Mixed Altera FPGA Chains* in the *Configuration Handbook*.

Configuration Stage

When the nSTATUS pin transitions high, the configuration device's OE pin also transitions high and the configuration device clocks data out serially to the FPGA using its internal oscillator. The Cyclone II device receives configuration data on its DATA0 pin and the clock is received on the DCLK pin. Data is latched into the FPGA on the rising edge of DCLK.

After the FPGA has received all configuration data successfully, it releases the open-drain CONF_DONE pin, which is pulled high by a pull-up resistor. Since the Cyclone II device's CONF_DONE pin is tied to the configuration device's nCS pin, the configuration device is disabled when CONF_DONE goes high. Enhanced configuration and EPC2 devices have an optional internal pull-up resistor on the nCS pin. You can turn this option on in the Quartus II software from the **General** tab of the **Device & Pin Options** dialog box. If you do not use this internal pull-up resistor, you need to connect an external 10-kΩ pull-up resistor to the nCS and CONF_DONE line. A low-to-high transition on CONF_DONE indicates configuration is complete, and the device can begin initialization.

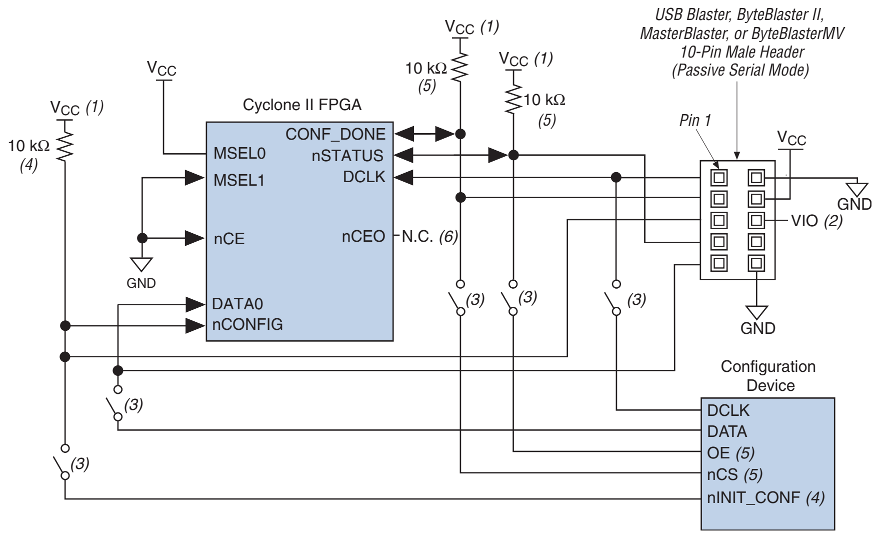
Initialization Stage

In Cyclone II devices, the default initialization clock source is the Cyclone II internal oscillator (typically 10 MHz). Cyclone II devices can also use the optional CLKUSR pin. If your design uses the internal oscillator, the Cyclone II device supplies itself with enough clock cycles for proper initialization. The advantage of using the internal oscillator is you do not need to use another device or source to send additional clock cycles to the CLKUSR pin during the initialization stage. Additionally, you can use of the CLKUSR pin as a user I/O pin, which means you have an additional user I/O pin.

If you want to delay the initialization of the device, you can use the CLKUSR pin. Using the CLKUSR pin allows you to control when the Cyclone II device enters user mode. You can delay the Cyclone II devices from entering user mode for an indefinite amount of time. You can turn on the **Enable user-supplied start-up clock (CLKUSR)** option in the Quartus II software from the **General** tab of the **Device & Pin Options** dialog box. Supplying a clock on CLKUSR does not affect the configuration process. After all configuration data is accepted and CONF_DONE goes high, Cyclone II devices require 299 clock cycles to properly initialize and support a CLKUSR f_{MAX} of 100 MHz.

An optional INIT_DONE pin is available, which signals the end of initialization and the start of user mode with a low-to-high transition. The **Enable INIT_DONE output** option is available in the Quartus II software from the **General** tab of the **Device & Pin Options** dialog box. If you use the INIT_DONE pin, an external 10-kΩ pull-up resistor pulls it high when the five common signals (nCONFIG, nSTATUS, DCLK, DATA0, and CONF_DONE) between the cable and the configuration device. You can also remove the configuration device from the board when configuring the FPGA with the cable. Figure 13–21 shows a combination of a configuration device and a download cable to configure an FPGA.

Figure 13–21. PS Configuration with a Download Cable & Configuration Device Circuit



Notes to Figure 13–21:

(1) The pull-up resistor should be connected to the same supply voltage as the configuration device.

(2) Pin 6 of the header is a V_{IO} reference voltage for the MasterBlaster output driver. V_{IO} should match the device's V_{CCIO}. Refer to the *MasterBlaster Serial/USB Communications Cable Data Sheet* for this value. In the ByteBlasterMV, this pin is a no connect. In the USB-Blaster and ByteBlaster II, this pin is connected to nCE when it is used for AS programming, otherwise it is a no connect.

(3) You should not attempt configuration with a download cable while a configuration device is connected to a Cyclone II device. Instead, you should either remove the configuration device from its socket when using the download cable or place a switch on the five common signals between the download cable and the configuration device.

(4) The nINIT_CONF pin (available on enhanced configuration devices and EPC2 devices only) has an internal pull-up resistor that is always active. This means an external pull-up resistor should not be used on the nINIT_CONF to nCONFIG line. The nINIT_CONF pin does not need to be connected if its functionality is not used. If nINIT_CONF is not used or not available (e.g., on EPC1 devices), nCONFIG must be pulled to V_{CC} either directly or through a resistor (if reconfiguration is required, a resistor is necessary).

(5) The enhanced configuration devices' OE and nCS pins have internal programmable pull-up resistors. If internal pull-up resistors are used, external pull-up resistors should not be used on these pins. The internal pull-up resistors are used by default in the Quartus II software. To turn off the internal pull-up resistors, check the **Disable nCS and OE pull-ups on configuration device** option when generating programming files.

(6) The nCEO pin can be left unconnected or used as a user I/O pin when it does not feed other device's nCE pin.

frequency (up to 40 MHz), which reduces your configuration time. In addition, Cyclone II devices can receive a compressed configuration bitstream and decompress this data on-the-fly in the AS or PS configuration scheme, which further reduces storage requirements and configuration time.

- Perform a SAMPLE/PRELOAD test cycle prior to the first EXTEST test cycle to ensure that known data is present at the device pins when the EXTEST mode is entered. If the OEJ update register contains a 0, the data in the OUTJ update register is driven out. The state must be known and correct to avoid contention with other devices in the system.
- Do not perform EXTEST testing during ICR. This instruction is supported before or after ICR, but not during ICR. Use the CONFIG_IO instruction to interrupt configuration, then perform testing, or wait for configuration to complete.
- If performing testing before configuration, hold the nCONFIG pin low.
- After configuration, any pins in a differential pin pair cannot be tested. Therefore, performing BST after configuration requires editing BSC group definitions that correspond to these differential pin pairs. The BSC group should be redefined as an internal cell. See the BSDL file for more information on editing.

For more information on boundary scan testing, contact Altera Applications.

Boundary-Scan Description Language (BSDL) Support

The Boundary-Scan Description Language (BSDL), a subset of VHDL, provides a syntax that allows you to describe the features of an IEEE Std. 1149.1 BST-capable device that can be tested. Test software development systems then use the BSDL files for test generation, analysis, and failure diagnostics. For more information, or to receive BSDL files for IEEE Std. 1149.1-compliant Cyclone II devices, visit the Altera web site at **www.altera.com**.

Conclusion

The IEEE Std. 1149.1 BST circuitry available in Cyclone II devices provides a cost-effective and efficient way to test systems that contain devices with tight lead spacing. Circuit boards with Altera and other IEEE Std. 1149.1-compliant devices can use the EXTEST, SAMPLE/PRELOAD, BYPASS, IDCODE, USERCODE, CLAMP, and HIGHZ modes to create serial patterns that internally test the pin connections between devices and check device operation.

References

Bleeker, H., P. van den Eijnden, and F. de Jong. *Boundary-Scan Test: A Practical Approach*. Eindhoven, The Netherlands: Kluwer Academic Publishers, 1993.

Institute of Electrical and Electronics Engineers, Inc. *IEEE Standard Test Access Port and Boundary-Scan Architecture* (IEEE Std 1149.1-2001). New York: Institute of Electrical and Electronics Engineers, Inc., 2001.